CHIPSUN 芯 阳 科 技

CSN6D036D7

Dual N-Ch Fast Switching MOSFETs

General Description

The CSN6D036D7 is the highest performance trench N-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The CSN6D036D7 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Product Summery

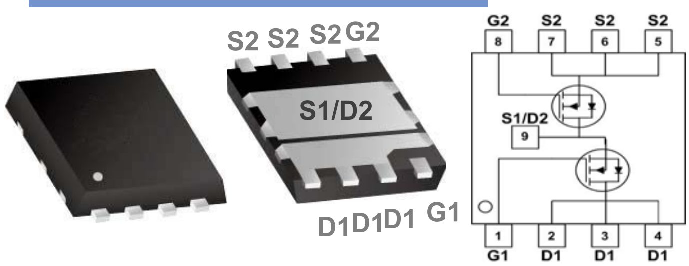
Green

CH	BVDSS	RDSON	ID
Die1	30V	9mΩ	57A
Die2	30V	5.5mΩ	72A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- CCFL Back-light Inverter

PRPAK5X6 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		Die1	Die2	
V_{DS}	Drain-Source Voltage	30	30	V
V_{GS}	Gate-Source Voltage	±20	±20	V
I_D@T_C=25℃	Continuous Drain Current, V_{GS} @ 10V[1]	57	72	A
I_D@T_C=100℃	Continuous Drain Current, V_{GS} @ 10V[1]	36	46	A
I_D@T_A=25℃	Continuous Drain Current, V_{GS} @ 10V[1]	12	15	A
I_D@T_A=70℃	Continuous Drain Current, V_{GS} @ 10V[1]	9.6	12	A
I_{DM}	Pulsed Drain Current[2]	130	160	A
EAS	Single Pulse Avalanche Energy[3]	130	252	mJ
I_{AS}	Avalanche Current	34	48	A
P_D@T_C=25℃	Total Power Dissipation[4]	46	46	W
P_D@T_A=25℃	Total Power Dissipation[4]	2	2	W
T_{STG}	Storage Temperature Range	-55 to 150	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	-55 to 150	℃

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{θJA}$	Thermal Resistance Junction-Ambient [1]	---	62	℃/W
$R_{θJC}$	Thermal Resistance Junction-Case[1]	---	2.7	℃/W

Rev A.01 D071111

Die1 N-Channel Electrical Characteristics (TJ=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	30	35	---	V
$\triangle BV_{DSS}/\triangle T_J$	BVDSS Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	0.024	---	V/℃
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V , I_D=30A	---	7.2	9	mΩ
		V_{GS}=4.5V , I_D=15A	---	10.5	13.5	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1.2	1.5	2.5	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-3.5	---	mV/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=24V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=24V , V_{GS}=0V , T_J=55℃	---	---	5	
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
gfs	Forward Transconductance	V_{DS}=5V , I_D=30A	---	42	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	1.45	2.4	Ω
Q_g	Total Gate Charge (4.5V)	V_{DS}=15V , V_{GS}=4.5V , I_D=15A	---	10.6	14.8	nC
Q_{gs}	Gate-Source Charge		---	4.2	5.9	
Q_{gd}	Gate-Drain Charge		---	4.0	5.6	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=15V , V_{GS}=10V , R_G=3.3Ω I_D=15A	---	6.4	12.8	ns
T_r	Rise Time		---	70.6	127	
$T_{d(off)}$	Turn-Off Delay Time		---	22.4	45	
T_f	Fall Time		---	8.0	16	
C_{iss}	Input Capacitance	V_{DS}=15V , V_{GS}=0V , f=1MHz	---	1127	1578	pF
C_{oss}	Output Capacitance		---	194	272	
C_{rss}	Reverse Transfer Capacitance		---	77	108	

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy[5]	V_{DD}=25V , L=0.1mH , I_{AS}=20A	45	---	---	mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current[1,6]	V_G=V_D=0V , Force Current	---	---	57	A
I_{SM}	Pulsed Source Current[2,6]		---	---	130	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1.2	V
t_{rr}	Reverse Recovery Time	IF=30A , dI/dt=100A/µs , T_J=25℃	---	12	---	nS
Q_{rr}	Reverse Recovery Charge		---	3.7	---	nC

Note :
1.The data tested by surface mounted on a 1 $inch^2$ FR-4 board with 2OZ copper.
2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%
3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=34A
4.The power dissipation is limited by 150℃ junction temperature
5.The Min. value is 100% EAS tested guarantee.
6.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Die2 N-Channel Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	30	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BVDSS Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	0.028	---	V/℃
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V , I_D=30A	---	4.5	5.5	mΩ
		V_{GS}=4.5V , I_D=15A	---	7.5	9	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1.2	1.5	2.5	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-6.16	---	mV/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=24V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=24V , V_{GS}=0V , T_J=55℃	---	---	5	
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
gfs	Forward Transconductance	V_{DS}=5V , I_D=30A	---	43	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	1.7	2.9	Ω
Q_g	Total Gate Charge (4.5V)	V_{DS}=15V , V_{GS}=4.5V , I_D=15A	---	20	28.0	nC
Q_{gs}	Gate-Source Charge		---	7.6	10.6	
Q_{gd}	Gate-Drain Charge		---	7.2	10.1	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=15V , V_{GS}=10V , R_G=3.3Ω I_D=15A	---	7.8	15.6	ns
T_r	Rise Time		---	15	27	
$T_{d(off)}$	Turn-Off Delay Time		---	37.3	75	
T_f	Fall Time		---	10.6	21.2	
C_{iss}	Input Capacitance	V_{DS}=15V , V_{GS}=0V , f=1MHz	---	2295	3213	pF
C_{oss}	Output Capacitance		---	267	374	
C_{rss}	Reverse Transfer Capacitance		---	210	294	

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy[5]	V_{DD}=25V , L=0.1mH , I_{AS}=24A	63	---	---	mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current[1,6]	V_G=V_D=0V , Force Current	---	---	72	A
I_{SM}	Pulsed Source Current[2,6]		---	---	160	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1	V
t_{rr}	Reverse Recovery Time	IF=30A , dI/dt=100A/µs , T_J=25℃	---	14	---	nS
Q_{rr}	Reverse Recovery Charge		---	5	---	nC

Note :

1.The data tested by surface mounted on a 1 $inch^2$ FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%

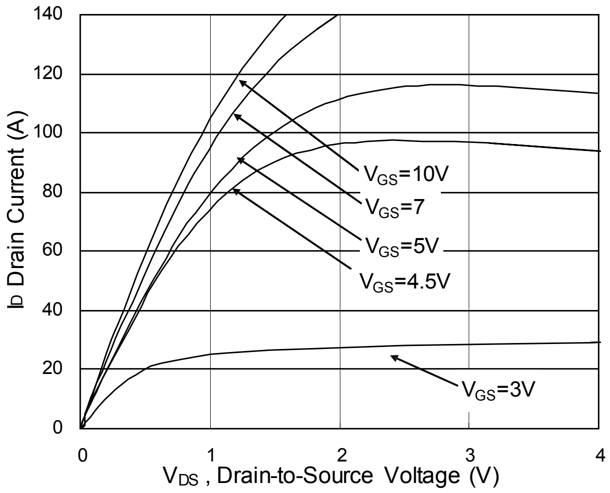
3.The EAS data shows Max. rating . The test condition is V_{DD}=-25V,V_{GS}=-10V,L=0.1mH,I_{AS}=48A

4.The power dissipation is limited by 150℃ junction temperature

5.The Min. value is 100% EAS tested guarantee.

6.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

N- Channel Typical Characteristics (Die1)



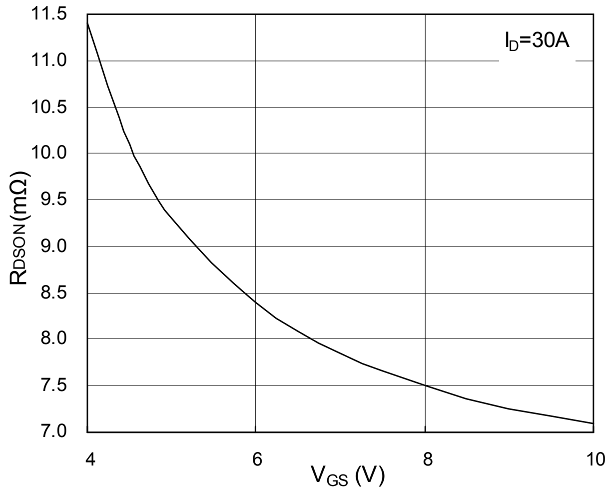
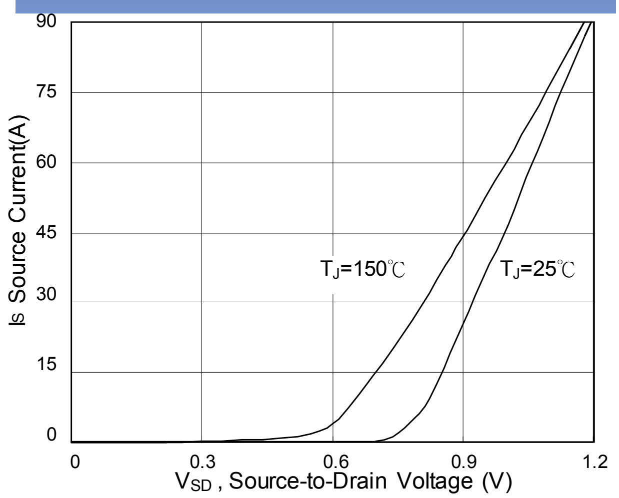


Fig.1 Typical Output Characteristics

Fig.2 On-Resistance vs. Gate-Source



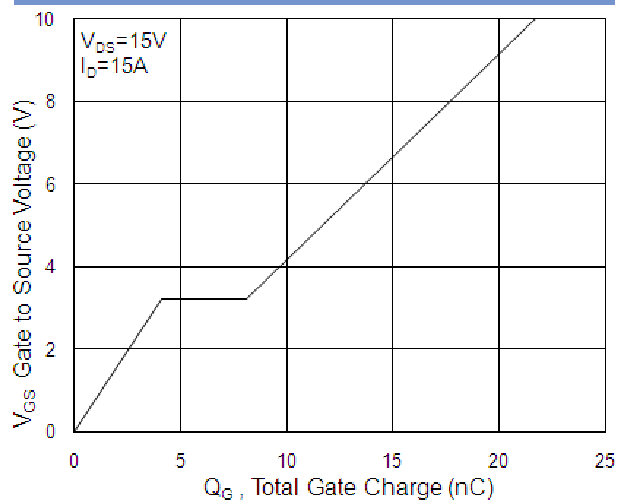
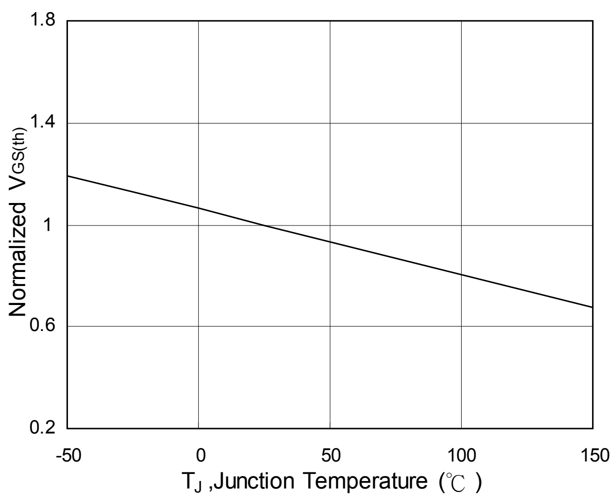


Fig.3 Forward Characteristics of Reverse

Fig.4 Gate-Charge Characteristics



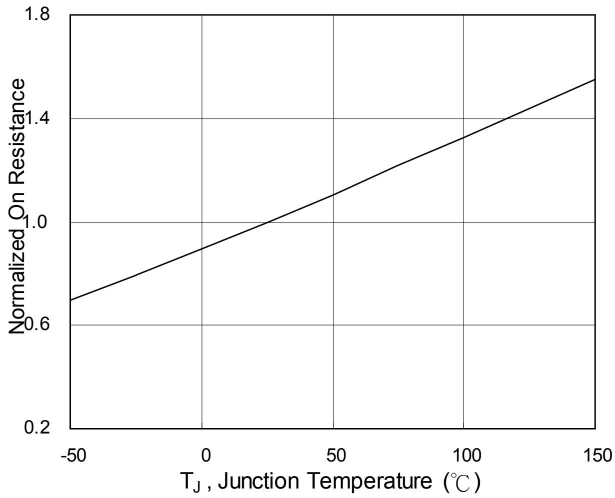


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

Fig.6 Normalized R_{DSON} vs. T_J

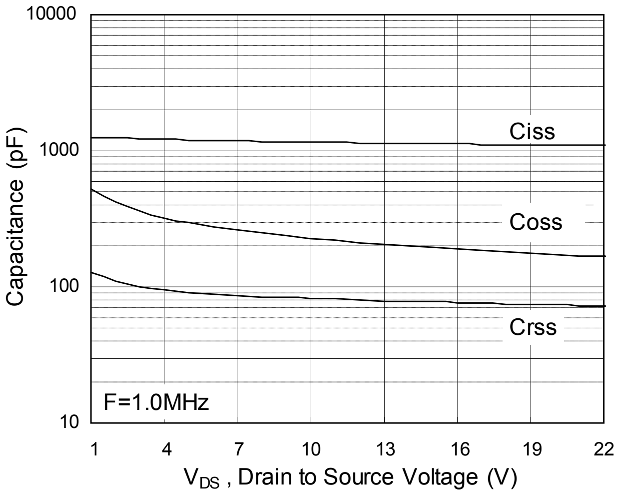


Fig.7 Capacitance

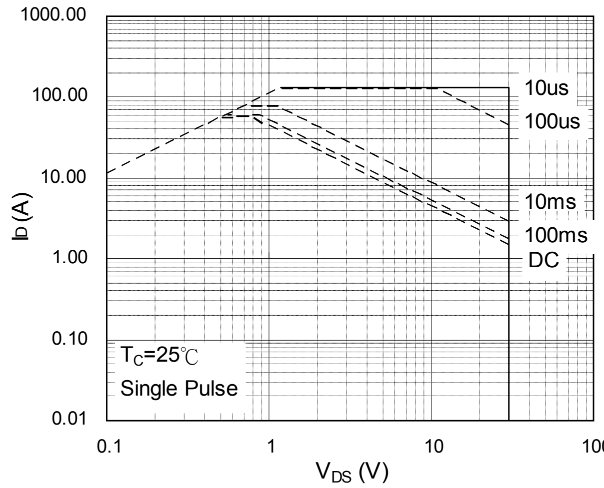


Fig.8 Safe Operating Area

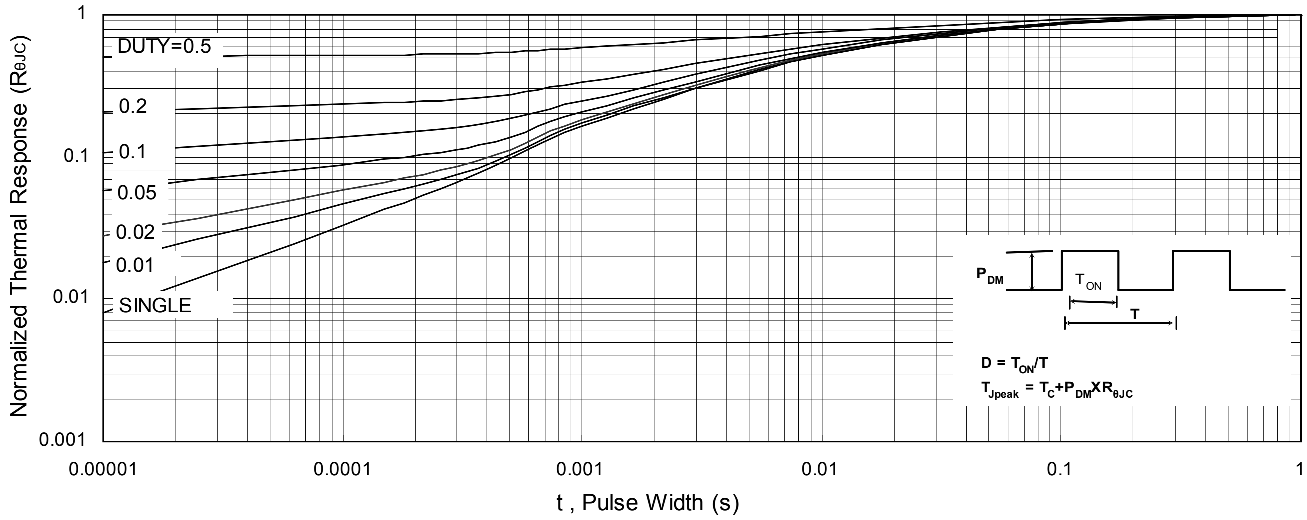


Fig.9 Normalized Maximum Transient Thermal Impedance

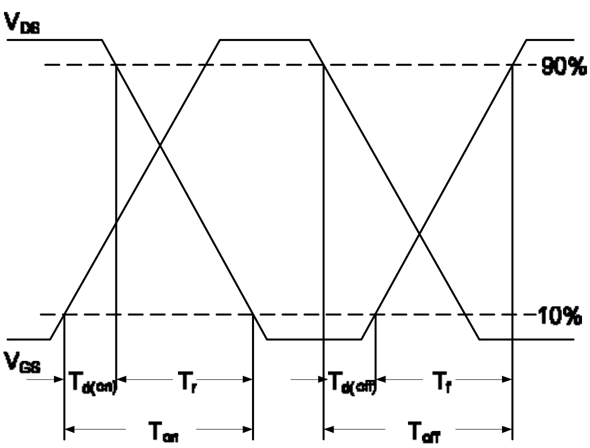


Fig.10 Switching Time Waveform

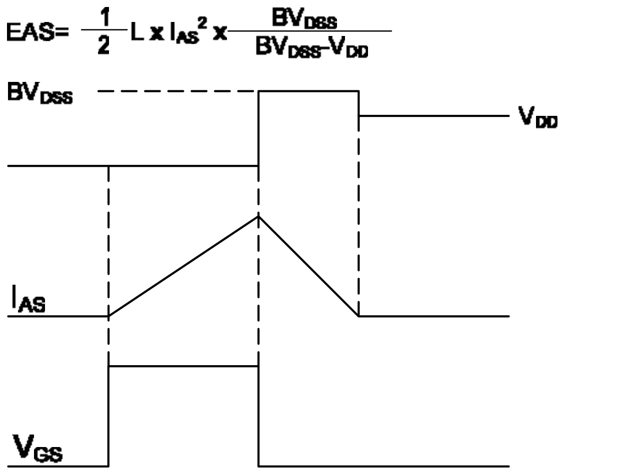


Fig.11 Unclamped Inductive Switching Waveform

N-Channel Typical Characteristics (Die2)

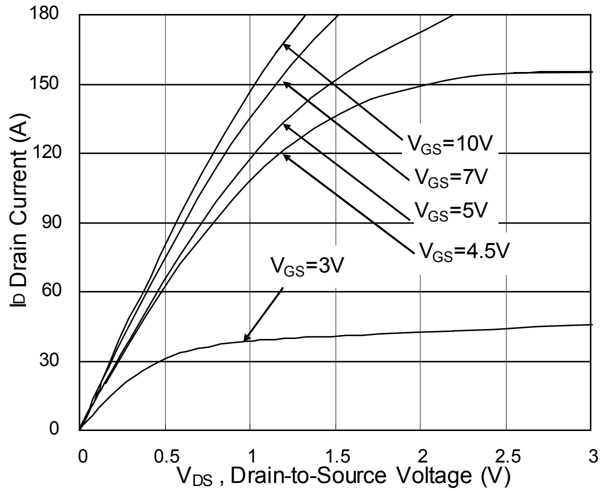


Fig.1 Typical Output Characteristics

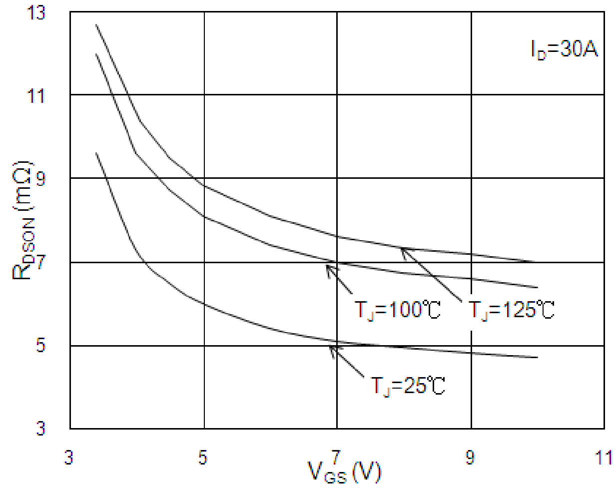


Fig.2 On-Resistance vs. G-S Voltage

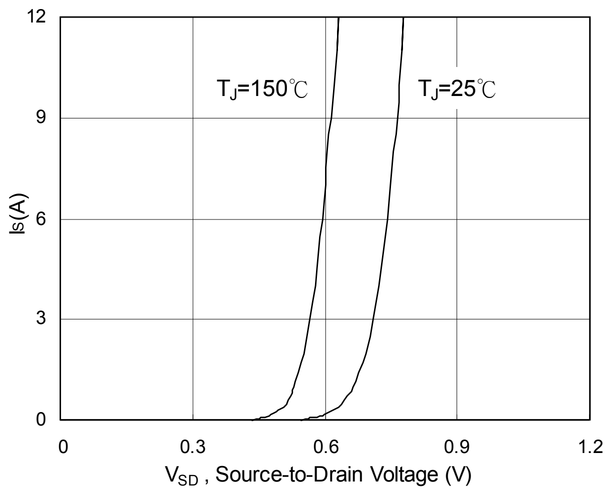


Fig.3 Forward Characteristics of Reverse

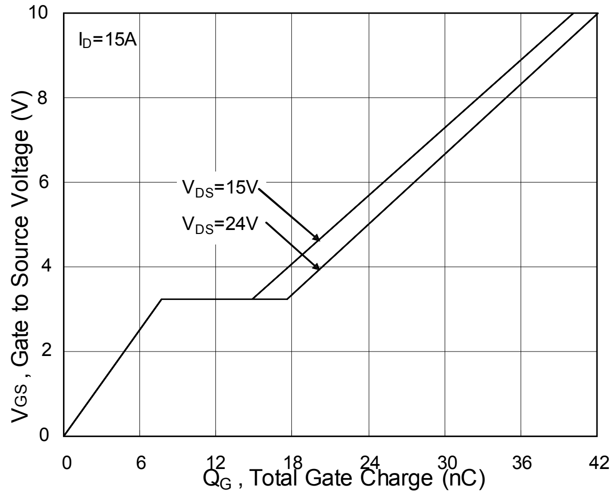


Fig.4 Gate-Charge Characteristics

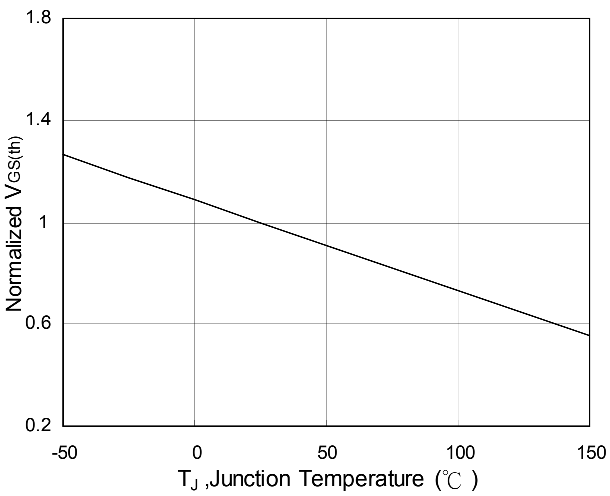


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

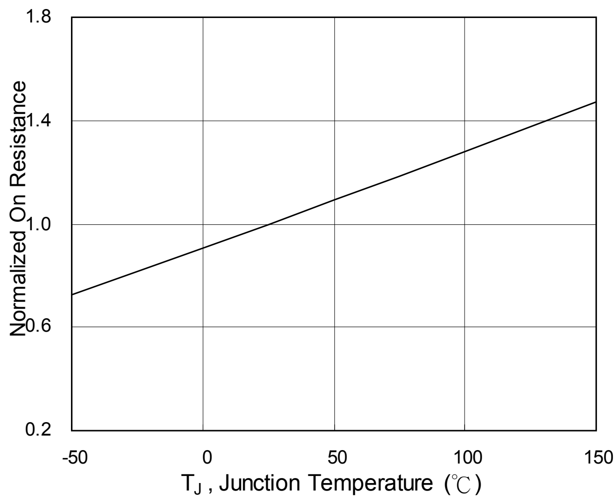


Fig.6 Normalized R_{DSON} vs. T_J

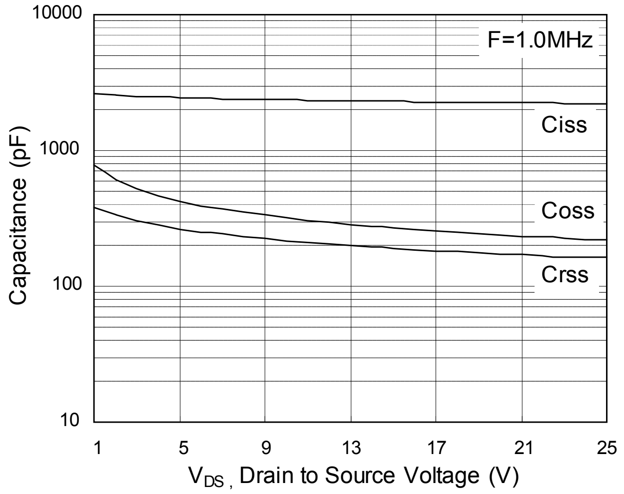


Fig.7 Capacitance

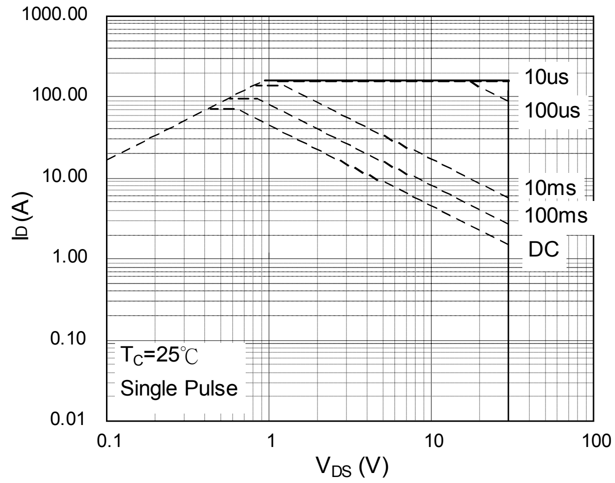


Fig.8 Safe Operating Area

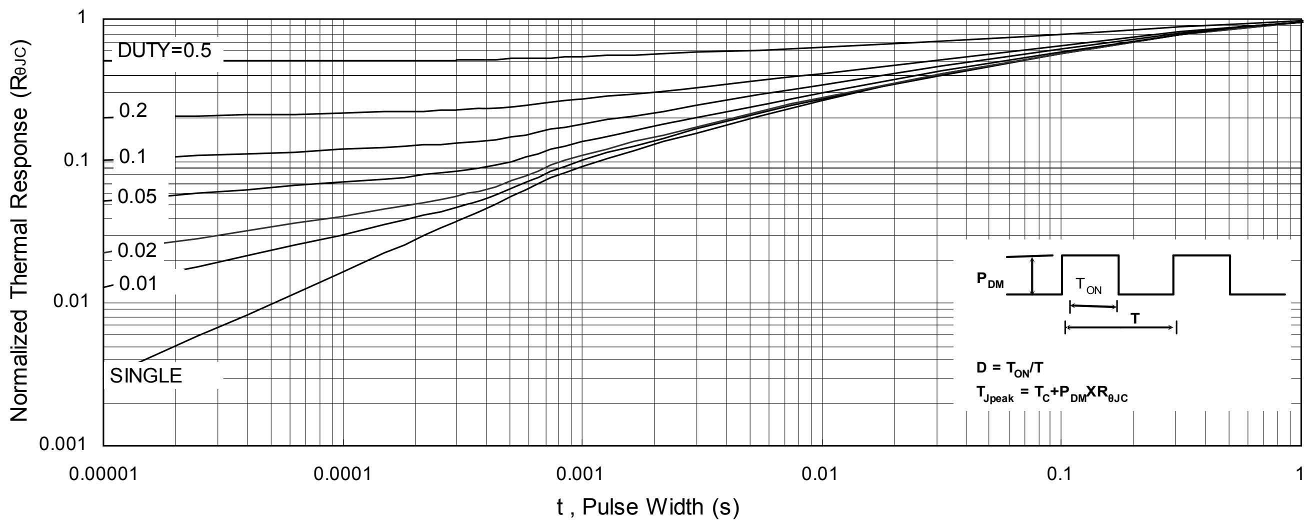


Fig.9 Normalized Maximum Transient Thermal Impedance

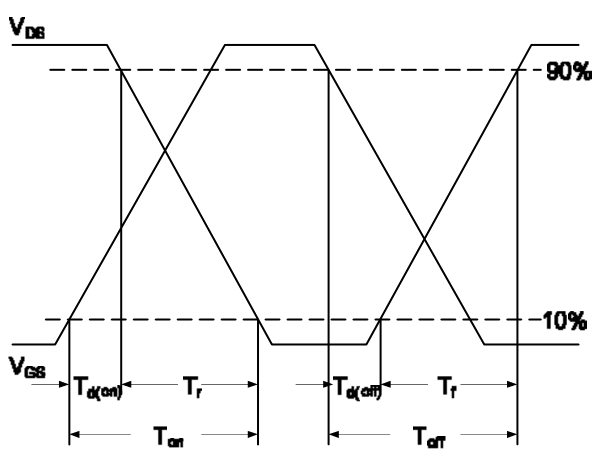


Fig.10 Switching Time Waveform

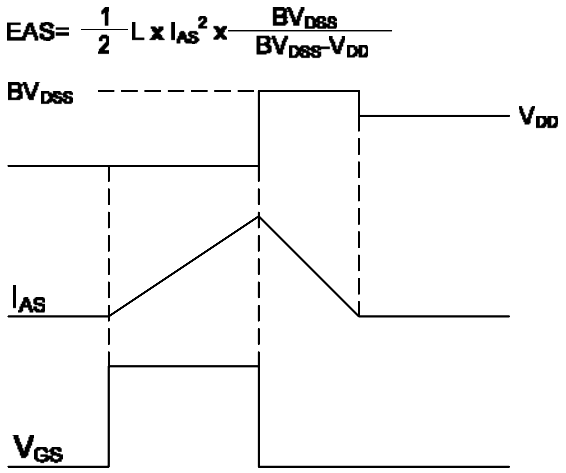


Fig.11 Unclamped Inductive Switching Waveform